

## ***III-V-on-silicon photonic integrated circuits for communication and sensing applications***

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We will review our work on the heterogeneous integration of III-V opto-electronic components on silicon photonic integrated circuits by die-to-wafer bonding and transfer printing technology. This includes high speed onto-electronic components for communication applications as well as light sources and photodetectors operating at 'non-telecom' wavelengths for application in bio-sensors and spectroscopic sensing systems.